PCA9548A

8-channel I²C switch with reset

Rev. 01 — 15 April 2005 Product data sheet

1. General description

The PCA9548A is an octal bi-directional translating switch controlled via the I²C-bus. The SCL/SDA upstream pair fans out to eight downstream pairs, or channels. Any individual SCx/SDx channel or combination of channels can be selected, determined by the contents of the programmable control register.

An active LOW reset input allows the PCA9548A to recover from a situation where one of the downstream I²C-buses is stuck in a LOW state. Pulling the $\overline{\text{RESET}}$ pin LOW resets the I²C-bus state machine and causes all the channels to be deselected as does the internal Power-on reset function.

The pass gates of the switches are constructed such that the V_{DD} pin can be used to limit the maximum high voltage which will be passed by the PCA9548A. This allows the use of different bus voltages on each pair, so that 1.8 V or 2.5 V or 3.3 V parts can communicate with 5 V parts without any additional protection. External pull-up resistors pull the bus up to the desired voltage level for each channel. All I/O pins are 5 V tolerant.

2. Features

- 1-of-8 bi-directional translating switches
- I²C-bus interface logic; compatible with SMBus standards
- Active LOW reset input
- 3 address pins allowing up to 8 devices on the I²C-bus
- Channel selection via I²C-bus, in any combination
- Power-up with all switch channels deselected
- Low R_{on} switches
- Allows voltage level translation between 1.8 V, 2.5 V, 3.3 V and 5 V buses
- No glitch on power-up
- Supports hot insertion
- Low stand-by current
- Operating power supply voltage range of 2.3 V to 5.5 V
- 5 V tolerant inputs
- 0 Hz to 400 kHz clock frequency
- ESD protection exceeds 2000 V HBM per JESD22-A114, 200 V MM per JESD22-A115, and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JEDEC Standard JESD78 which exceeds 100 mA
- Three packages offered: SO24, TSSOP24, and HVQFN24

PHILIPS

3. Ordering information

Table 1: Ordering information

T_{amb} = –40 °C to +85 °C

Type number	Package		
	Name	Description	Version
PCA9548ABS	HVQFN24	plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 4 × 4 × 0.85 mm	SOT616-1
PCA9548AD	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1
PCA9548APW	TSSOP24	plastic thin shrink small outline package; 24 leads; body width 4.4 mm	SOT355-1

4. Marking

Table 2: Marking codes

Type number	Topside mark
PCA9548ABS	548A
PCA9548AD	PCA9548AD
PCA9548APW	PCA9548A

5. Block diagram

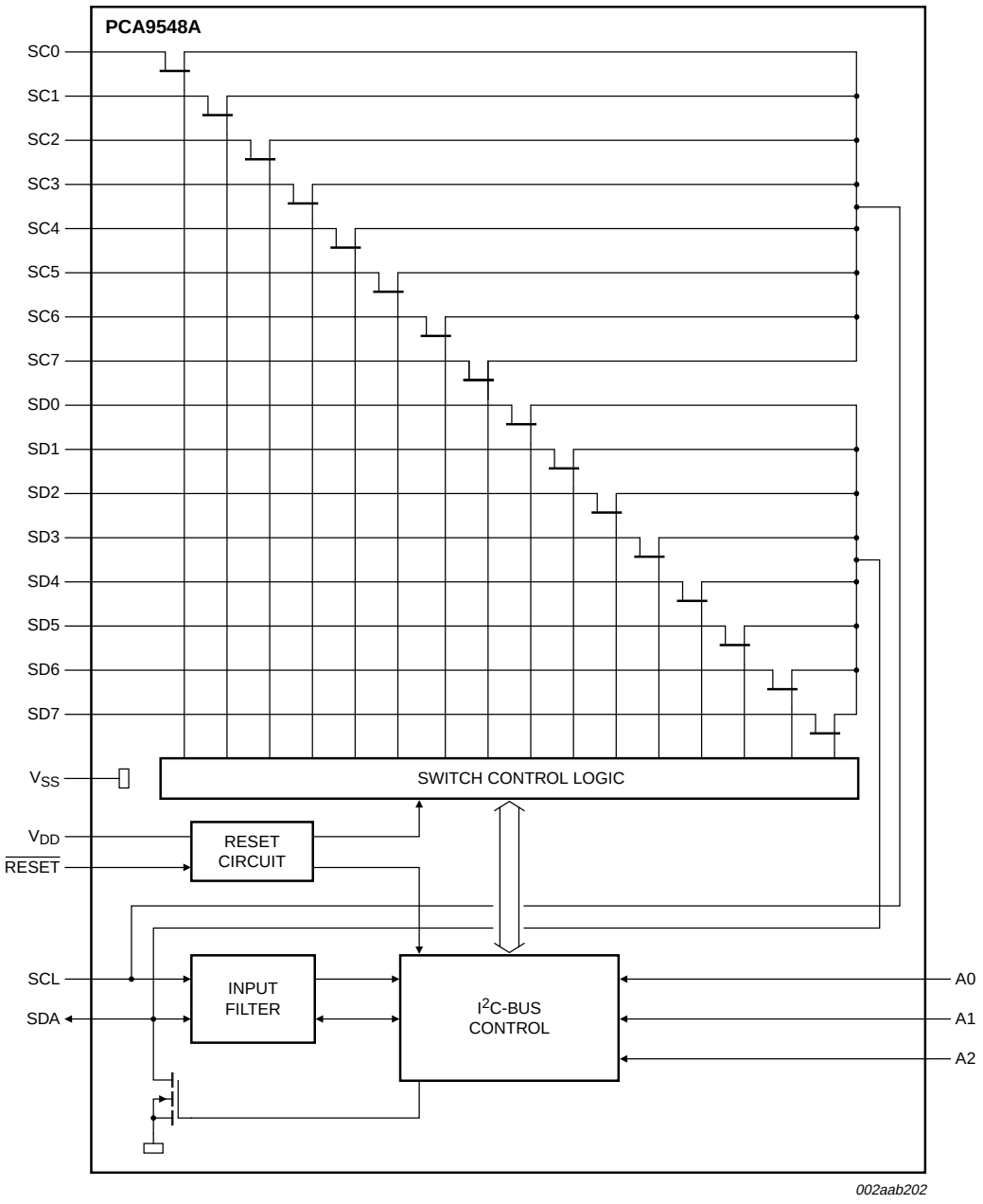


Fig 1. Block diagram of PCA9548A

6. Pinning information

6.1 Pinning

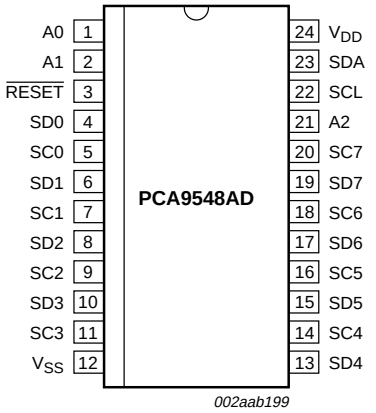


Fig 2. Pin configuration for SO24

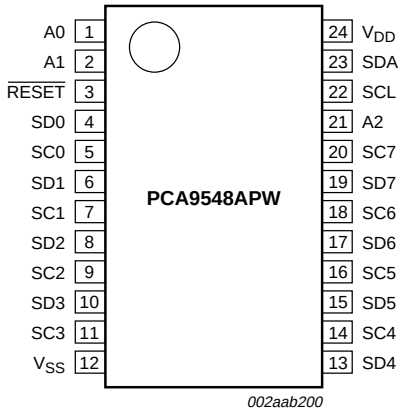
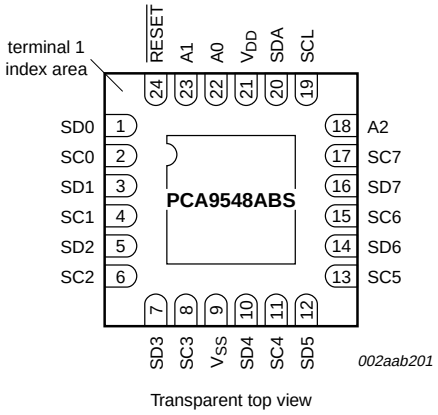


Fig 3. Pin configuration for TSSOP24



Transparent top view

Fig 4. Pin configuration for HVQFN24 (transparent top view)

6.2 Pin description

Table 3: Pin description

Symbol	Pin		Description
	SO, TSSOP	HVQFN	
A0	1	22	address input 0
A1	2	23	address input 1
$\overline{\text{RESET}}$	3	24	active LOW reset input
SD0	4	1	serial data 0
SC0	5	2	serial clock 0
SD1	6	3	serial data 1
SC1	7	4	serial clock 1
SD2	8	5	serial data 2
SC2	9	6	serial clock 2
SD3	10	7	serial data 3
SC3	11	8	serial clock 3
V_{SS}	12	9 [1]	supply ground
SD4	13	10	serial data 4
SC4	14	11	serial clock 4
SD5	15	12	serial data 5
SC5	16	13	serial clock 5
SD6	17	14	serial data 6
SC6	18	15	serial clock 6
SD7	19	16	serial data 7
SC7	20	17	serial clock 7
A2	21	18	address input 2
SCL	22	19	serial clock line
SDA	23	20	serial data line
V_{DD}	24	21	supply voltage

[1] HVQFN package die supply ground is connected to both the V_{SS} pin and the exposed center pad. The V_{SS} pin must be connected to supply ground for proper device operation. For enhanced thermal, electrical, and board-level performance, the exposed pad needs to be soldered to the board using a corresponding thermal pad on the board, and for proper heat conduction through the board thermal vias need to be incorporated in the PCB in the thermal pad region.

7. Functional description

Refer to Figure 1 “Block diagram of PCA9548A” on page 3.

7.1 Device address

Following a START condition, the bus master must output the address of the slave it is accessing. The address of the PCA9548A is shown in Figure 5. To conserve power, no internal pull-up resistors are incorporated on the hardware selectable address pins and they must be pulled HIGH or LOW.

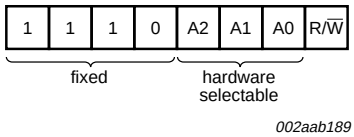


Fig 5. Slave address

The last bit of the slave address defines the operation to be performed. When set to logic 1 a read is selected, while a logic 0 selects a write operation.

7.2 Control register

Following the successful acknowledgement of the slave address, the bus master will send a byte to the PCA9548A, which will be stored in the control register. If multiple bytes are received by the PCA9548A, it will save the last byte received. This register can be written and read via the I²C-bus.

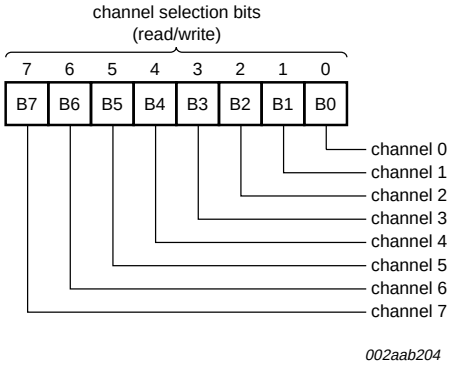


Fig 6. Control register

7.2.1 Control register definition

One or several SCx/SDx downstream pair, or channel, is selected by the contents of the control register. This register is written after the PCA9548A has been addressed. The 2 LSBs of the control byte are used to determine which channel is to be selected. When a channel is selected, the channel will become active after a STOP condition has been placed on the I²C-bus. This ensures that all SCx/SDx lines will be in a HIGH state when the channel is made active, so that no false conditions are generated at the time of connection.

Table 4: Control register: Write—channel selection; Read—channel status

B7	B6	B5	B4	B3	B2	B1	B0	Command
X	X	X	X	X	X	X	0	channel 0 disabled
							1	channel 0 enabled
X	X	X	X	X	X	0	X	channel 1 disabled
						1		channel 1 enabled
X	X	X	X	X	0	X	X	channel 2 disabled
					1			channel 2 enabled
X	X	X	X	0	X	X	X	channel 3 disabled
				1				channel 3 enabled
X	X	X	0	X	X	X	X	channel 4 disabled
			1					channel 4 enabled
X	X	0	X	X	X	X	X	channel 5 disabled
		1						channel 5 enabled
X	0	X	X	X	X	X	X	channel 6 disabled
	1							channel 6 enabled
0	X	X	X	X	X	X	X	channel 7 disabled
1								channel 7 enabled

Remark: Multiple channels can be enabled at the same time. Example: B7 = 0, B6 = 1, B5 = 0, B4 = 0, B3 = 1, B2 = 1, B1 = 0, B0 = 0, means that channels 7, 5, 4, 1 and 0 are disabled and channels 6, 3, and 2 are enabled. Care should be taken not to exceed the maximum bus capacitance. Default condition is all zeroes.

7.3 $\overline{\text{RESET}}$ input

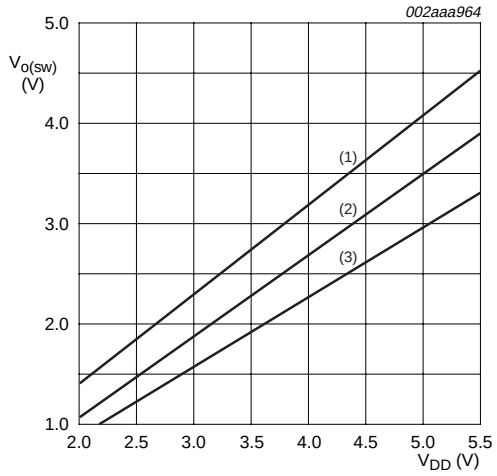
The $\overline{\text{RESET}}$ input is an active LOW signal which may be used to recover from a bus fault condition. By asserting this signal LOW for a minimum of t_{WL}, the PCA9548A will reset its register and I²C-bus state machine and will deselect all channels. The $\overline{\text{RESET}}$ input must be connected to V_{DD} through a pull-up resistor.

7.4 Power-on reset

When power is applied to V_{DD}, an internal Power-On Reset (POR) holds the PCA9548A in a reset condition until V_{DD} has reached V_{POR}. At this point, the reset condition is released and the PCA9548A register and I²C-bus state machine are initialized to their default states—all zeroes—causing all the channels to be deselected. Thereafter, V_{DD} must be lowered below 0.2 V to reset the device.

7.5 Voltage translation

The pass gate transistors of the PCA9548A are constructed such that the V_{DD} voltage can be used to limit the maximum voltage that will be passed from one I²C-bus to another.



(1) maximum

(2) typical

(3) minimum

Fig 7. Pass gate voltage versus supply voltage

Figure 7 shows the voltage characteristics of the pass gate transistors (note that the PCA9548A is only tested at the points specified in Section 11 “Static characteristics” of this data sheet). In order for the PCA9548A to act as a voltage translator, the $V_{O(sw)}$ voltage should be equal to, or lower than the lowest bus voltage. For example, if the main bus was running at 5 V, and the downstream buses were 3.3 V and 2.7 V, then $V_{O(sw)}$ should be equal to or below 2.7 V to effectively clamp the downstream bus voltages. Looking at Figure 7, we see that $V_{O(sw)(max)}$ will be at 2.7 V when the PCA9548A supply voltage is 3.5 V or lower, so the PCA9548A supply voltage could be set to 3.3 V. Pull-up resistors can then be used to bring the bus voltages to their appropriate levels (see Figure 14).

More Information can be found in Application Note *AN262: PCA954X family of I2C/SMBus multiplexers and switches*.

8. Characteristics of the I²C-bus

The I²C-bus is for 2-way, 2-line communication between different ICs or modules. The two lines are a serial data line (SDA) and a serial clock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

8.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as control signals (see Figure 8).

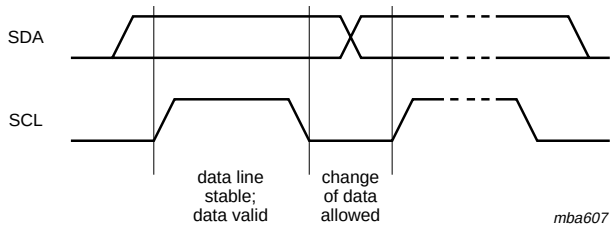


Fig 8. Bit transfer

8.2 START and STOP conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line while the clock is HIGH is defined as the START condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition (P) (see Figure 9).

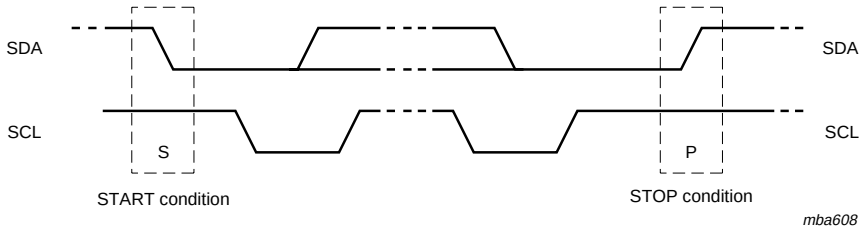


Fig 9. Definition of START and STOP conditions

8.3 System configuration

A device generating a message is a ‘transmitter’, a device receiving is the ‘receiver’. The device that controls the message is the ‘master’ and the devices which are controlled by the master are the ‘slaves’ (see Figure 10).

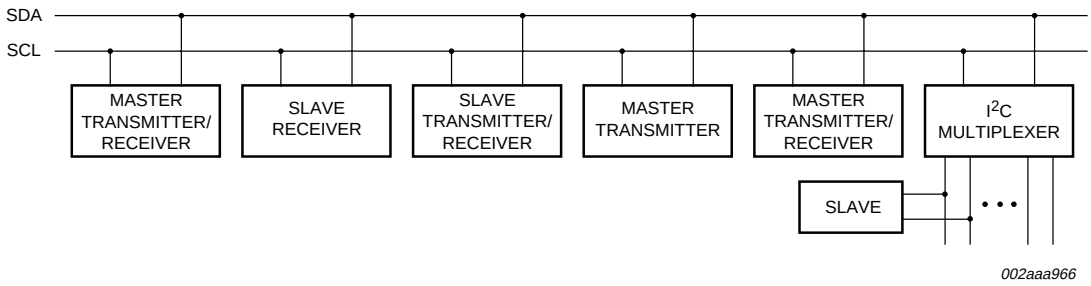


Fig 10. System configuration

8.4 Acknowledge

The number of data bytes transferred between the START and the STOP conditions from transmitter to receiver is not limited. Each byte of eight bits is followed by one acknowledge bit. The acknowledge bit is a HIGH level put on the bus by the transmitter, whereas the master generates an extra acknowledge related clock pulse.

A slave receiver which is addressed must generate an acknowledge after the reception of each byte. Also, a master must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse; setup and hold times must be taken into account.

A master receiver must signal an end of data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event, the transmitter must leave the data line HIGH to enable the master to generate a STOP condition.

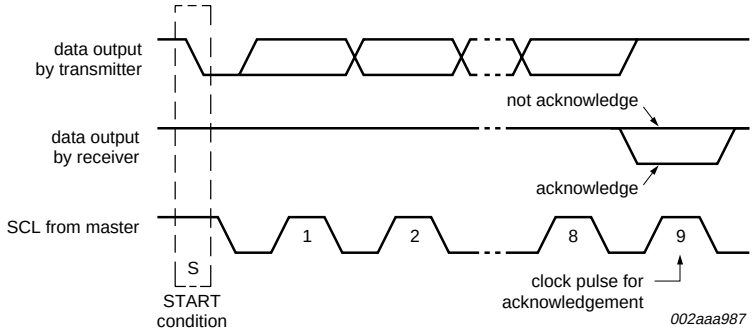


Fig 11. Acknowledgement on the I²C-bus

8.5 Bus transactions

Data is transmitted to the PCA9548A control register using the Write mode as shown in Figure 12.

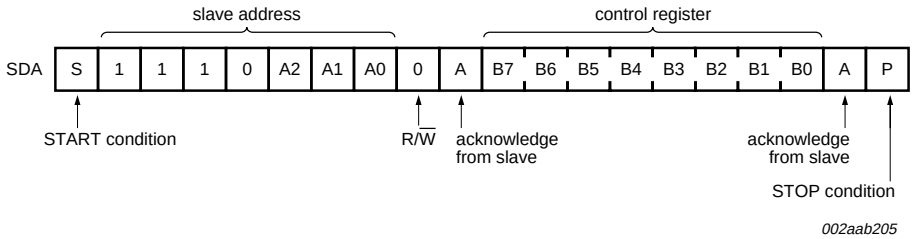


Fig 12. Write control register

Data is read from PCA9548A using the Read mode as shown in Figure 13.

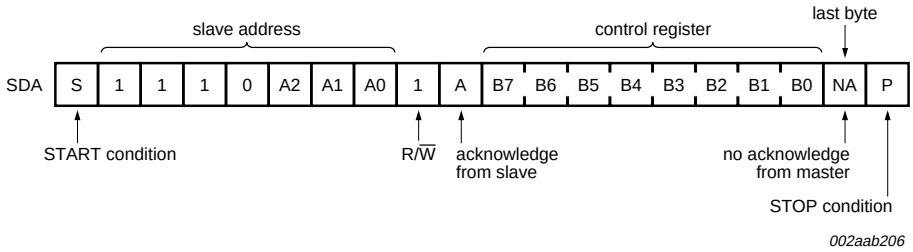


Fig 13. Read control register

9. Application design-in information

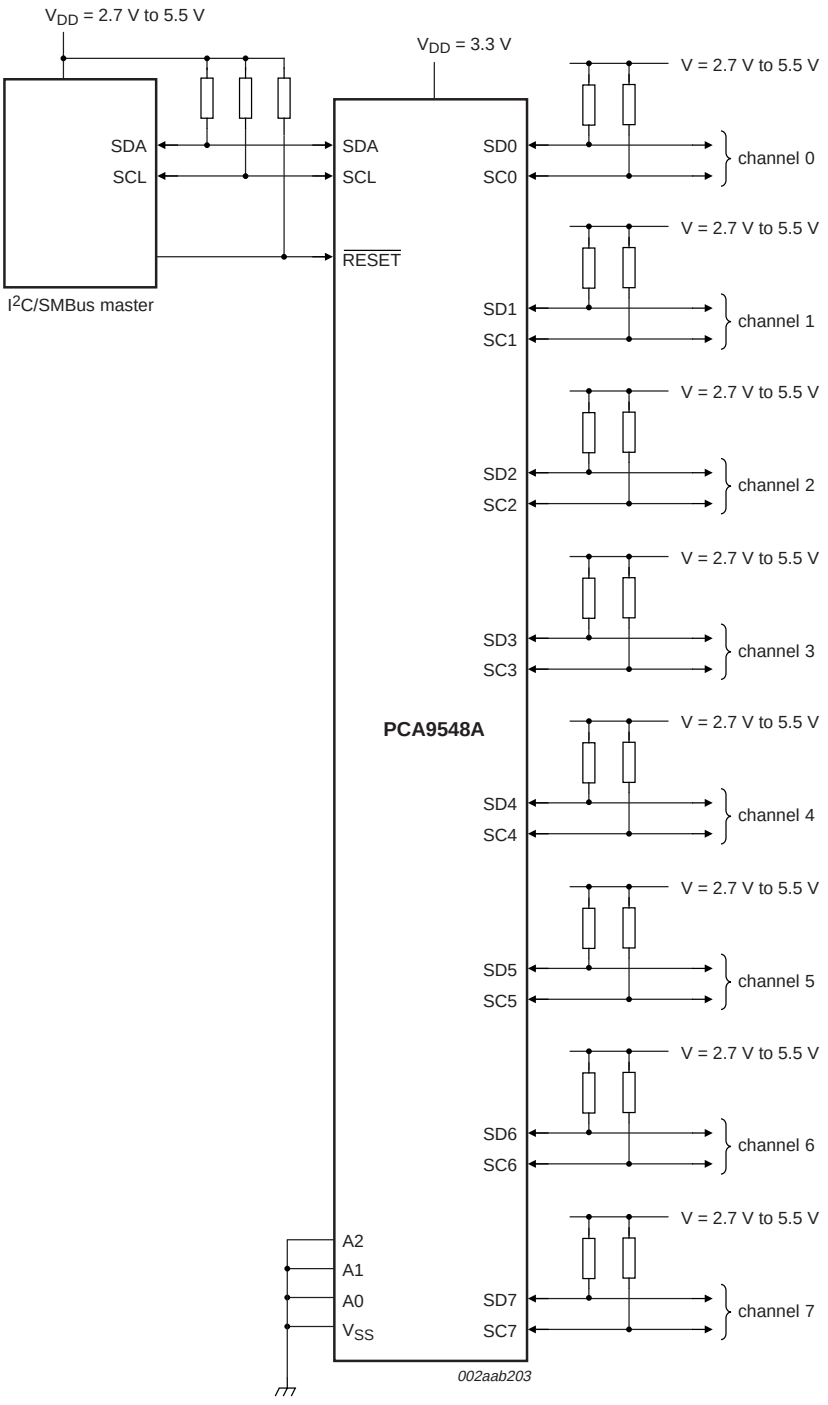


Fig 14. Typical application

10. Limiting values

Table 5: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to V_{SS} (ground = 0 V). [1]

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		–0.5	+7.0	V
V_I	input voltage		–0.5	+7.0	V
I_I	input current		-	±20	mA
I_O	output current		-	±25	mA
I_{DD}	supply current		-	±100	mA
I_{SS}	ground supply current		-	±100	mA
P_{tot}	total power dissipation		-	400	mW
T_{stg}	storage temperature		–60	+150	°C
T_{amb}	operating ambient temperature		–40	+85	°C

[1] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

11. Static characteristics

Table 6: DC characteristics

V_{DD} = 2.3 V to 3.6 V; V_{SS} = 0 V; T_{amb} = –40 °C to +85 °C; unless otherwise specified.
See Table 7 on page 15 for V_{DD} = 4.5 V to 5.5 V.[1]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supply						
V_{DD}	supply voltage		2.3	-	3.6	V
I_{DD}	supply current	operating mode; V_{DD} = 3.6 V; no load; $V_I = V_{DD}$ or V_{SS}; f_{SCL} = 100 kHz	-	30	50	µA
I_{stb}	standby current	standby mode; V_{DD} = 3.6 V; no load; $V_I = V_{DD}$ or V_{SS}	-	0.1	1	µA
V_{POR}	power-on reset voltage	no load; $V_I = V_{DD}$ or V_{SS} [2]	-	1.6	2.1	V
Input SCL; input/output SDA						
V_{IL}	LOW-level input voltage		–0.5	-	$0.3V_{DD}$	V
V_{IH}	HIGH-level input voltage		$0.7V_{DD}$	-	6	V
I_{OL}	LOW-level output current	V_{OL} = 0.4 V	3	6	-	mA
		V_{OL} = 0.6 V	6	9	-	mA
I_L	leakage current	$V_I = V_{DD}$ or V_{SS}	–1	-	+1	µA
C_i	input capacitance	$V_I = V_{SS}$	-	15	21	pF
Select inputs A0 to A2, $\overline{RESET}$						
V_{IL}	LOW-level input voltage		–0.5	-	$0.3V_{DD}$	V
V_{IH}	HIGH-level input voltage		$0.7V_{DD}$	-	V_{DD} + 0.5	V
I_{LI}	input leakage current	pin at V_{DD} or V_{SS}	–1	-	+1	µA
C_i	input capacitance	$V_I = V_{SS}$	-	2	5	pF
Pass gate						
R_{on}	on-state resistance	V_{DD} = 3.0 V to 3.6 V; V_O = 0.4 V; I_O = 15 mA	5	11	30	Ω
		V_{DD} = 2.3 V to 2.7 V; V_O = 0.4 V; I_O = 10 mA	7	16	55	Ω
$V_{o(sw)}$	switch output voltage	$V_{i(sw)} = V_{DD}$ = 3.3 V; $I_{o(sw)}$ = –100 µA	-	1.9	-	V
		$V_{i(sw)} = V_{DD}$ = 3.0 V to 3.6 V; $I_{o(sw)}$ = –100 µA	1.6	-	2.8	V
		$V_{i(sw)} = V_{DD}$ = 2.5 V; $I_{o(sw)}$ = –100 µA	-	1.5	-	V
		$V_{i(sw)} = V_{DD}$ = 2.3 V to 2.7 V; $I_{o(sw)}$ = –100 µA	1.1	-	2.0	V
I_L	leakage current	$V_I = V_{DD}$ or V_{SS}	–1	-	+1	µA
C_{io}	input/output capacitance	$V_I = V_{SS}$	-	3	5	pF

[1] For operation between published voltage ranges, refer to the worst-case parameter in both ranges.

[2] V_{DD} must be lowered to 0.2 V in order to reset part.

Table 7: DC characteristics

V_{DD} = 4.5 V to 5.5 V; V_{SS} = 0 V; T_{amb} = –40 °C to +85 °C; unless otherwise specified.
See Table 6 on page 14 for V_{DD} = 2.3 V to 3.6 V.[1]

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Supply							
V_{DD}	supply voltage			4.5	-	5.5	V
I_{DD}	supply current	operating mode; V_{DD} = 5.5 V; no load; V_I = V_{DD} or V_{SS}; f_{SCL} = 100 kHz		-	65	100	µA
I_{stb}	standby current	standby mode; V_{DD} = 5.5 V; no load; V_I = V_{DD} or V_{SS}		-	0.2	1	µA
V_{POR}	power-on reset voltage	no load; V_I = V_{DD} or V_{SS}	[2]	-	1.7	2.1	V
Input SCL; input/output SDA							
V_{IL}	LOW-level input voltage			–0.5	-	0.3V_{DD}	V
V_{IH}	HIGH-level input voltage			0.7V_{DD}	-	6	V
I_{OL}	LOW-level output current	V_{OL} = 0.4 V		3	-	-	mA
		V_{OL} = 0.6 V		6	-	-	mA
I_{IL}	LOW-level input current	V_I = V_{SS}		–1	-	1	µA
I_{IH}	HIGH-level input current	V_I = V_{DD}		–1	-	1	µA
C_i	input capacitance	V_I = V_{SS}		-	15	21	pF
Select inputs A0 to A2, $\overline{\text{RESET}}$							
V_{IL}	LOW-level input voltage			–0.5	-	0.3V_{DD}	V
V_{IH}	HIGH-level input voltage			0.7V_{DD}	-	V_{DD} + 0.5	V
I_{LI}	input leakage current	pin at V_{DD} or V_{SS}		–1	-	1	µA
C_i	input capacitance	V_I = V_{SS}		-	2	5	pF
Pass gate							
R_{on}	on-state resistance	V_{DD} = 4.5 V to 5.5 V; V_O = 0.4 V; I_O = 15 mA		4	9	24	Ω
$V_{o(sw)}$	switch output voltage	$V_{i(sw)}$ = V_{DD} = 5.0 V; $I_{o(sw)}$ = –100 µA		-	3.6	-	V
		$V_{i(sw)}$ = V_{DD} = 4.5 V to 5.5 V; $I_{o(sw)}$ = –100 µA		2.6	-	4.5	V
I_L	leakage current	V_I = V_{DD} or V_{SS}		–1	-	+1	µA
C_{io}	input/output capacitance	V_I = V_{SS}		-	3	5	pF

[1] For operation between published voltage ranges, refer to the worst-case parameter in both ranges.

[2] V_{DD} must be lowered to 0.2 V in order to reset part.

12. Dynamic characteristics

Table 8: Dynamic characteristics

Symbol	Parameter	Conditions	Standard-mode I²C-bus		Fast-mode I²C-bus		Unit
			Min	Max	Min	Max	
t_{PD}	propagation delay from SDA to SDn, or SCL to SCn		-	0.3 [1]	-	0.3 [1]	ns
f_{SCL}	SCL clock frequency		0	100	0	400	kHz
t_{BUF}	bus free time between a STOP and START condition		4.7	-	1.3	-	µs
$t_{HD;STA}$	Hold time (repeated) START condition. After this period, the first clock pulse is generated.		4.0	-	0.6	-	µs
t_{LOW}	LOW period of the SCL clock		4.7	-	1.3	-	µs
t_{HIGH}	HIGH period of the SCL clock		4.0	-	0.6	-	µs
$t_{SU;STA}$	setup time for a repeated START condition		4.7	-	0.6	-	µs
$t_{SU;STO}$	setup time for STOP condition		4.0	-	0.6	-	µs
$t_{HD;DAT}$	data hold time		0 [2]	3.45	0 [2]	0.9	µs
$t_{SU;DAT}$	data setup time		250	-	100	-	ns
t_r	rise time of both SDA and SCL signals		-	1000	$20 + 0.1C_b$ [3]	300	ns
t_f	fall time of both SDA and SCL signals		-	300	$20 + 0.1C_b$ [3]	300	µs
C_b	capacitive load for each bus line		-	400	-	400	µs
t_{SP}	pulse width of spikes which must be suppressed by the input filter		-	50	-	50	ns
$t_{VD;DAT}$	data valid time	HIGH-to-LOW [4]	-	1	-	1	µs
		LOW-to-HIGH [4]	-	0.6	-	0.6	µs
$t_{VD;ACK}$	data valid acknowledge		-	1	-	1	µs
$\overline{RESET}$							
$t_{w(rst)L}$	LOW-level reset time		4	-	4	-	ns
t_{rst}	reset time (SDA clear)		500	-	500	-	ns
$t_{REC;STA}$	recovery time to START condition		0	-	0	-	ns

[1] Pass gate propagation delay is calculated from the 20 Ω typical R_{on} and the 15 pF load capacitance.

[2] A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the $V_{IH(min)}$ of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

[3] C_b = total capacitance of one bus line in pF.

[4] Measurements taken with 1 kΩ pull-up resistor and 50 pF load.

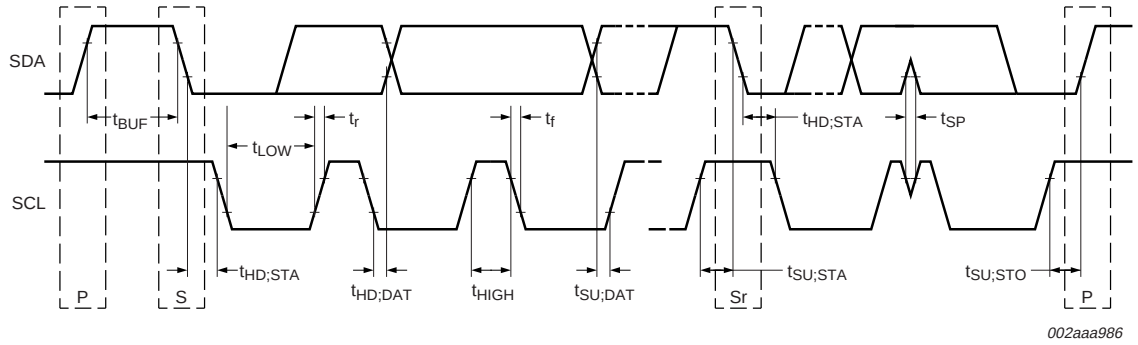


Fig 15. Definition of timing on the I²C-bus

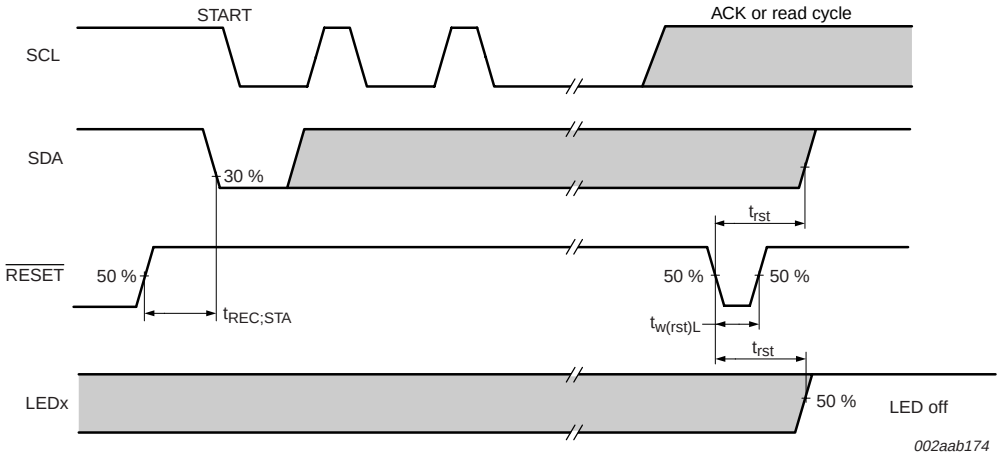


Fig 16. Definition of $\overline{\text{RESET}}$ timing

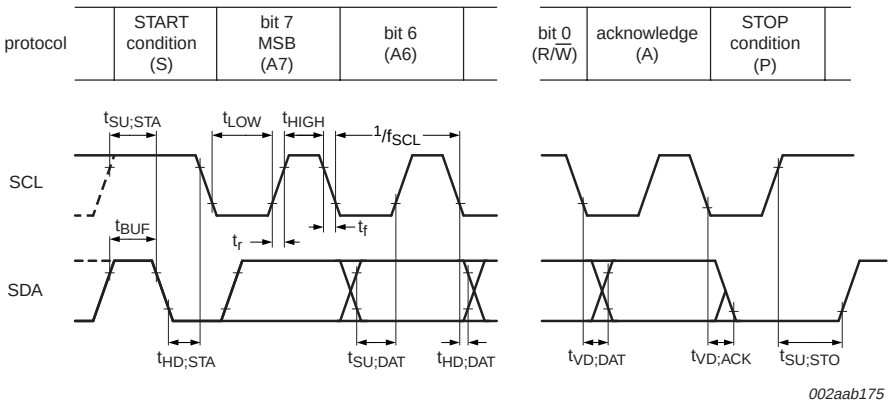
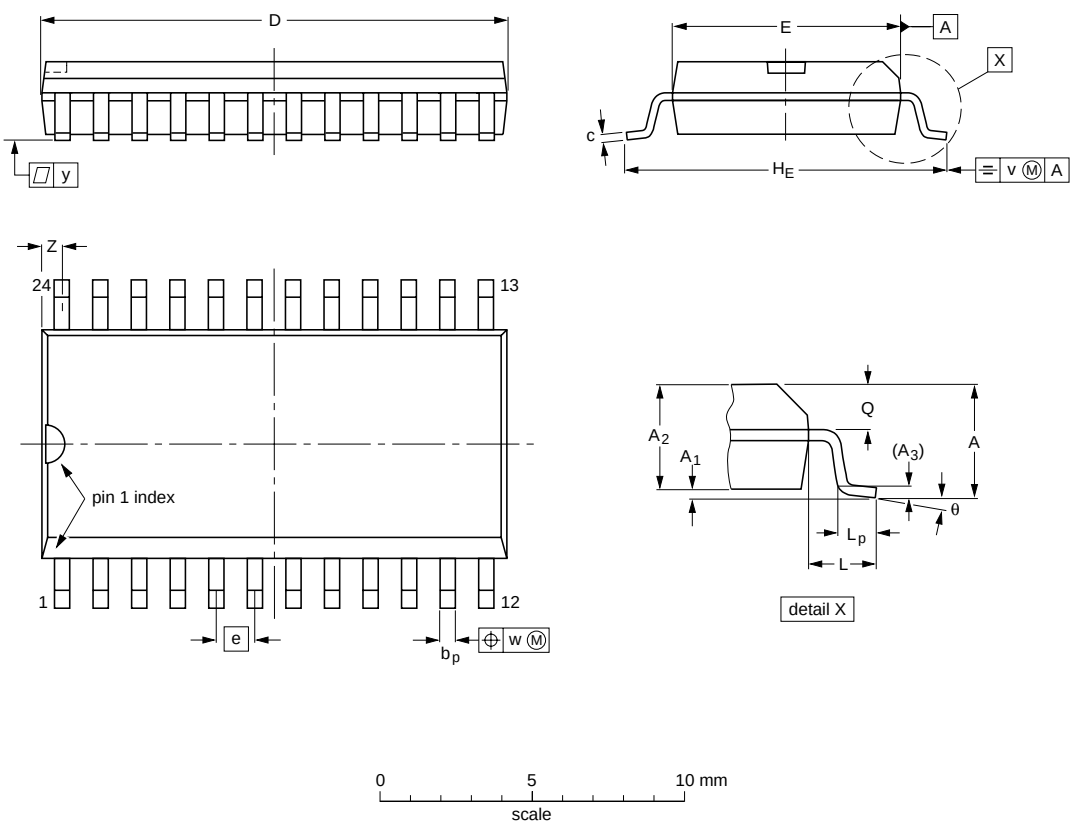


Fig 17. I²C-bus timing diagram

13. Package outline

SO24: plastic small outline package; 24 leads; body width 7.5 mm **SOT137-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

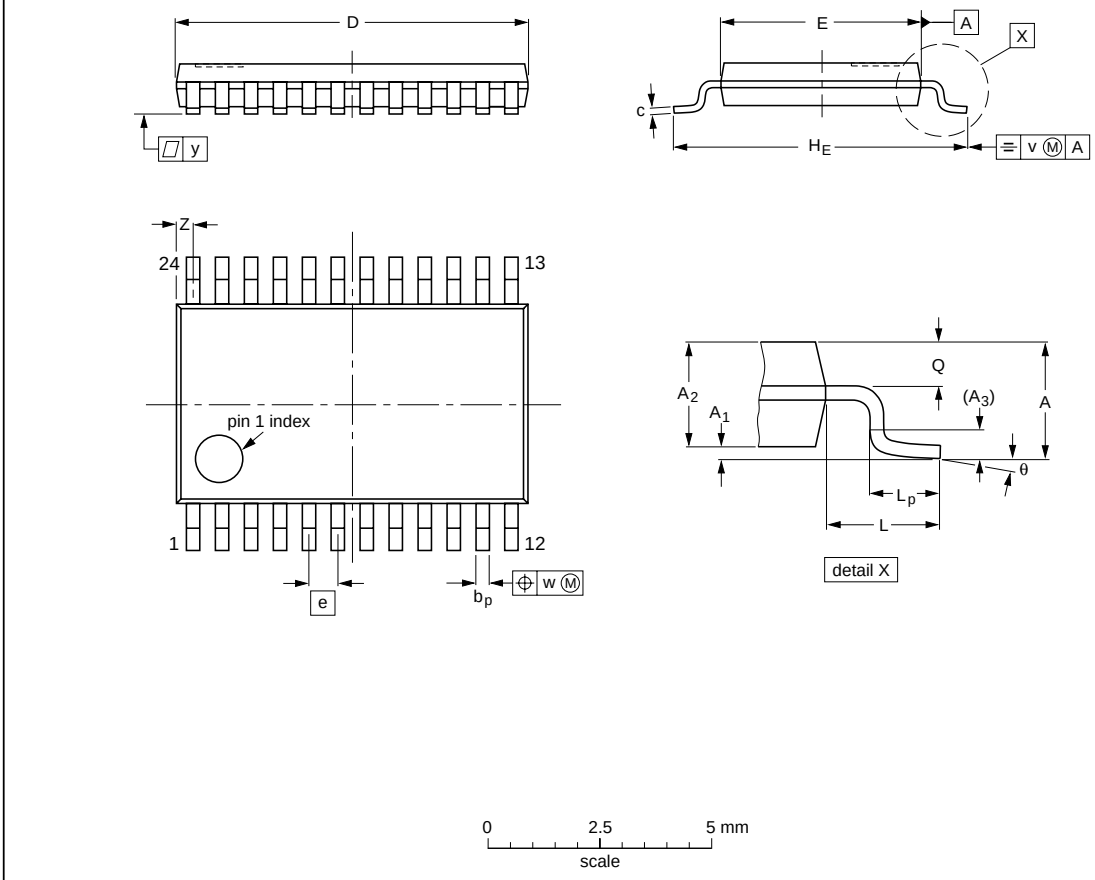
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT137-1	075E05	MS-013				~~99-12-27~~ 03-02-19

Fig 18. Package outline SOT137-1 (SO24)

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm **SOT355-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D(1)	E(2)	e	H_E	L	L_p	Q	v	w	y	Z(1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

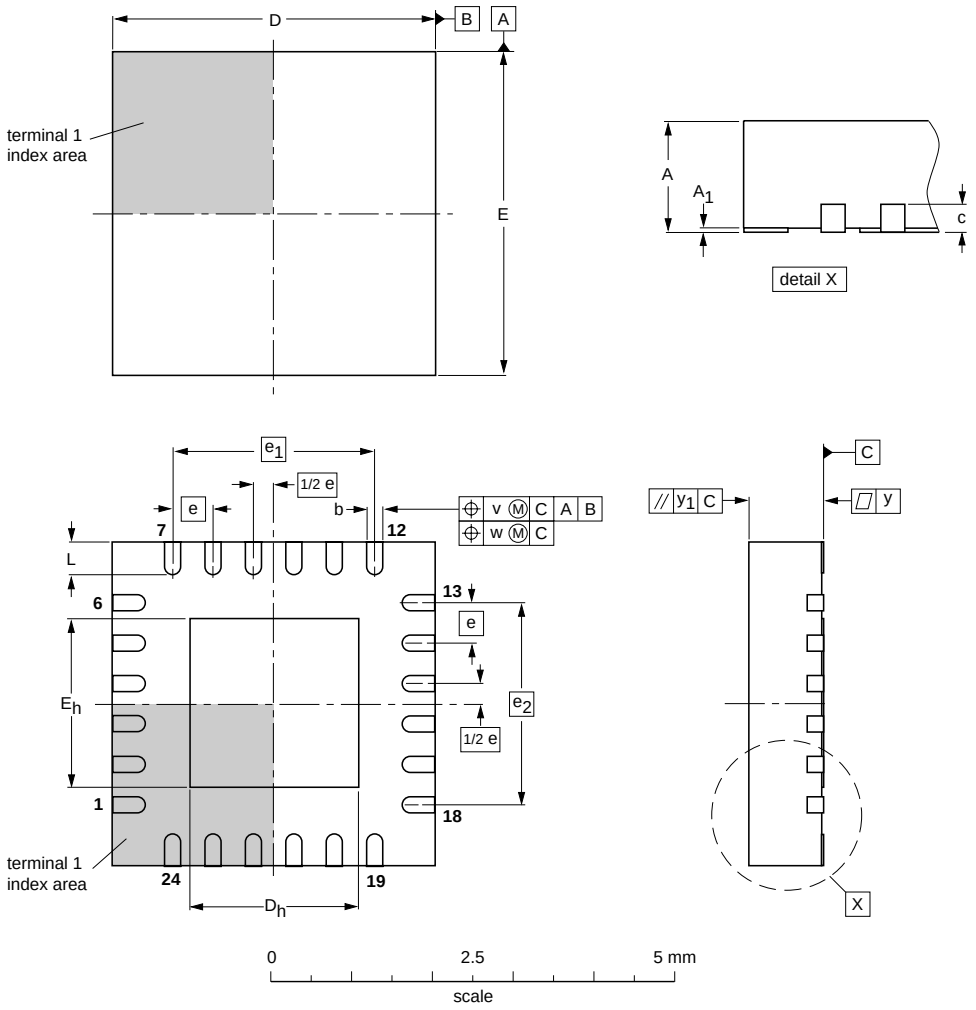
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT355-1		MO-153				~~99-12-27~~ 03-02-19

Fig 19. Package outline SOT355-1 (TSSOP24)

HVQFN24: plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 4 x 4 x 0.85 mm **SOT616-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A(1) max.	A1	b	c	D(1)	Dh	E(1)	Eh	e	e1	e2	L	v	w	y	y1
mm	1	0.05 0.00	0.30 0.18	0.2	4.1 3.9	2.25 1.95	4.1 3.9	2.25 1.95	0.5	2.5	2.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT616-1	- - -	MO-220	- - -			~~01-08-08~~ 02-10-22

Fig 20. Package outline SOT616-1 (HVQFN24)

14. Soldering

14.1 Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *Data Handbook IC26; Integrated Circuit Packages* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

14.2 Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement. Driven by legislation and environmental forces the worldwide use of lead-free solder pastes is increasing.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 seconds and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 °C to 270 °C depending on solder paste material. The top-surface temperature of the packages should preferably be kept:

- below 225 °C (SnPb process) or below 245 °C (Pb-free process)
  - for all BGA, HTSSON..T and SSOP..T packages
  - for packages with a thickness ≥ 2.5 mm
  - for packages with a thickness < 2.5 mm and a volume ≥ 350 mm^3 so called thick/large packages.
- below 240 °C (SnPb process) or below 260 °C (Pb-free process) for packages with a thickness < 2.5 mm and a volume < 350 mm^3 so called small/thin packages.

Moisture sensitivity precautions, as indicated on packing, must be respected at all times.

14.3 Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;

– smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time of the leads in the wave ranges from 3 seconds to 4 seconds at 250 °C or 265 °C, depending on solder material applied, SnPb or Pb-free respectively.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

14.4 Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 seconds to 5 seconds between 270 °C and 320 °C.

14.5 Package related soldering information

Table 9: Suitability of surface mount IC packages for wave and reflow soldering methods

Package [1]	Soldering method	
	Wave	Reflow [2]
BGA, HTSSON..T [3], LBGA, LFBGA, SQFP, SSOP..T [3], TFBGA, VFBGA, XSON	not suitable	suitable
DHVQFN, HBCC, HBGA, HLQFP, HSO, HSOP, HSQFP, HSSON, HTQFP, HTSSOP, HVQFN, HVSON, SMS	not suitable [4]	suitable
PLCC [5], SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended [5] [6]	suitable
SSOP, TSSOP, VSO, VSSOP	not recommended [7]	suitable
CWQCCN..L [8], PMFP [9], WQCCN..L [8]	not suitable	not suitable

[1] For more detailed information on the BGA packages refer to the *(LF)BGA Application Note* (AN01026); order a copy from your Philips Semiconductors sales office.

[2] All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods*.

[3] These transparent plastic packages are extremely sensitive to reflow soldering conditions and must on no account be processed through more than one soldering cycle or subjected to infrared reflow soldering with peak temperature exceeding 217 °C ± 10 °C measured in the atmosphere of the reflow oven. The package body peak temperature must be kept as low as possible.

[4] These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.

[5] If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.

[6] Wave soldering is suitable for LQFP, QFP and TQFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.

[7] Wave soldering is suitable for SSOP, TSSOP, VSO and VSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

[8] Image sensor packages in principle should not be soldered. They are mounted in sockets or delivered pre-mounted on flex foil. However, the image sensor package can be mounted by the client on a flex foil by using a hot bar soldering process. The appropriate soldering profile can be provided on request.

[9] Hot bar soldering or manual soldering is suitable for PMFP packages.

15. Abbreviations

Table 10: Abbreviations

Acronym	Description
CDM	Charged Device Model
ESD	Electro Static Discharge
HBM	Human Body Model
IC	Integrated Circuit
LSB	Least Significant Bit
MM	Machine Model
MSB	Most Significant Bit
PCB	Printed-Circuit Board
POR	Power-On Reset

16. Revision history

Table 11: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
PCA9548A_1	20050415	Product data sheet	-	9397 750 13297	-

17. Data sheet status

Level	Data sheet status [1]	Product status [2] [3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

18. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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21. Contents

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